

## PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Wen-Chi Lin</td> <td>09/09/2013</td> </tr> <tr> <td>Ching-Sheng Cheng</td> <td>09/09/2013</td> </tr> <tr> <td>Tseng-I Lin</td> <td>09/09/2013</td> </tr> </tbody> </table>	Name	Execution Date	Wen-Chi Lin	09/09/2013	Ching-Sheng Cheng	09/09/2013	Tseng-I Lin	09/09/2013	
Name	Execution Date								
Wen-Chi Lin	09/09/2013								
Ching-Sheng Cheng	09/09/2013								
Tseng-I Lin	09/09/2013								
RECEIVING PARTY DATA									
Name:	Realtek Semiconductor Corp.								
Street Address:	2 Innovation Rd. II, Science Park								
City:	HsinChu								
State/Country:	TAIWAN								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14024606</td> </tr> </tbody> </table>	Property Type	Number	Application Number:	14024606					
Property Type	Number								
Application Number:	14024606								
CORRESPONDENCE DATA									
Fax Number:	7039974517								
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Date:	09/11/2013								
Total Attachments: 2 source=1748070#page1.tif source=1748070#page2.tif									

CH \$40.00 14024606

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Wen-Chi Lin Nationality: TW

Name: Ching-Sheng Cheng Nationality: TW

Name: Tseng-I Lin Nationality: TW

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: Realtek Semiconductor Corp.

Address: 2 Innovation Rd. II, Science Park, HsinChu 30076, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"MOBILE HIGH-DEFINITION LINK DATA CONVERTER AND MOBILE  
HIGH-DEFINITION LINK DATA CONVERTING METHOD"

Which is found in :

- (a) + U.S. patent application executed on even date  
(b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_  
(c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_  
(d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_  
(e) \_\_\_\_\_ International application no. \_\_\_\_\_

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this SEP 09 2013 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Wen-Chi Lin

Wen-Chi Lin

Ching-Sheng Cheng

Ching-Sheng Cheng

Tseng-I Lin

Tseng-I Lin